



Microwave Ceramics and Modules	Filter
Filter for WLAN [5470-5725] MHz	B69842N5597A255

Preliminary data



Features

- SMD filter consisting of coupled resonators with stepped impedances
- $\text{MgTiO}_3\text{-CaTiO}_3$ ($\epsilon_r = 21$ / $TC_f = 0 \pm 10$ ppm/K) with a coating of copper ($10\mu\text{m}$) and tin ($>5\mu\text{m}$)
- Excellent reflow solderability, no migration effect due to copper/tin metallization

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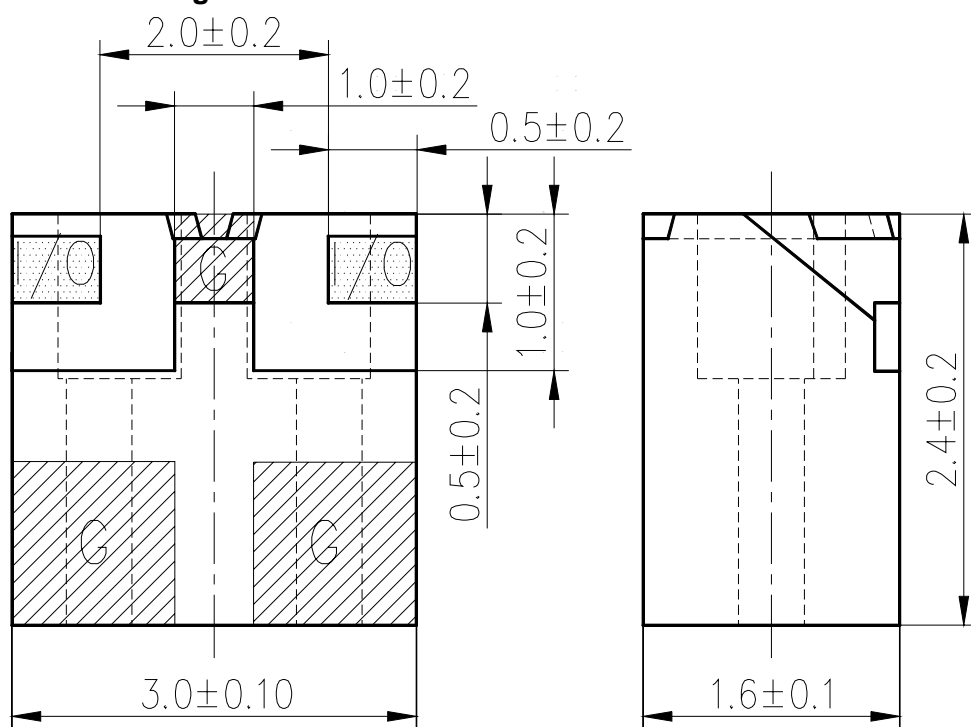
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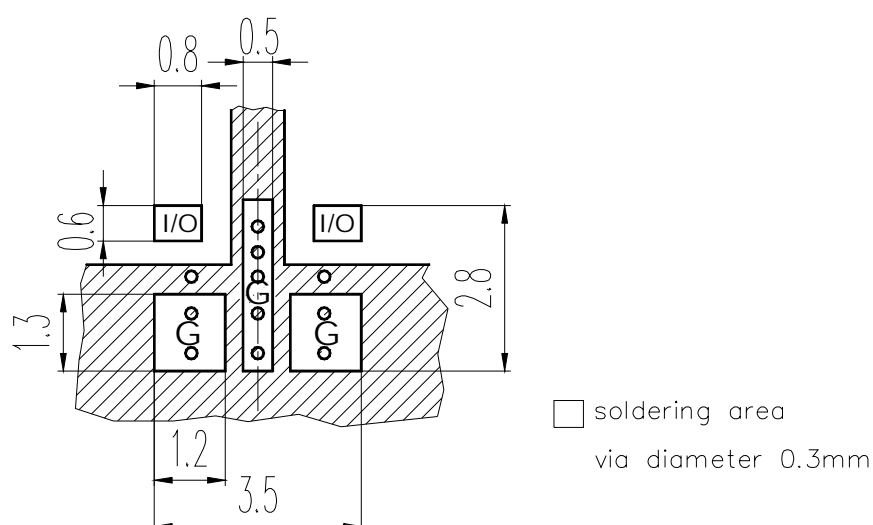
Preliminary data

Component drawing



S2H11_010601.DWG→WMF

Recommended footprint



FOOTPR_240502.DWG→WMF

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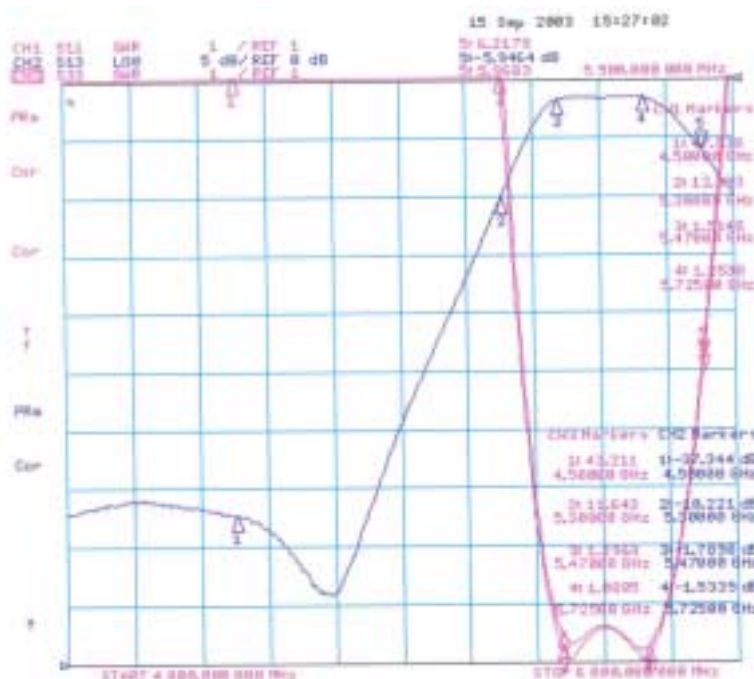
Characteristics

		min.	typ.	max.	
Center frequency	f_c	-	5597.5	-	MHz
Insertion loss	α_{IL}		1.3	1.6	dB
Passband	B	255			MHz
Amplitude ripple (peak - peak)	$\Delta\alpha$				dB
Standing wave ratio	SWR		1.5	2.0	
Impedance	Z		50		Ω
Power	P			1.0	W
Attenuation	α				
	at DC to 4500 MHz	35	40		dB
	at 5300 MHz	8			dB
	at 5900 MHz	5			dB

Maximum ratings

IEC climatic category (IEC 68-1)		- 40/+ 90/56	
Operating temperature	T_{op}	-40 / + 85	°C

Typical passband characteristic



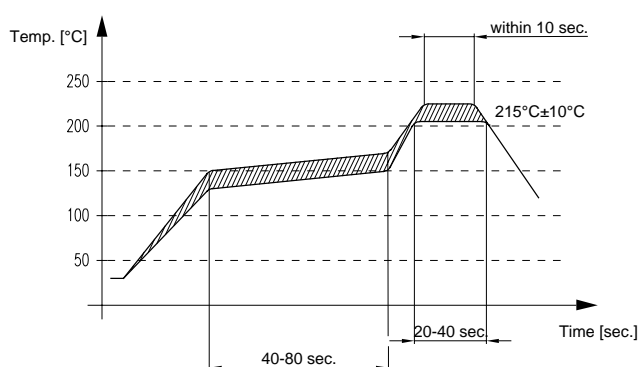
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ZNr.: 577 (FILT95_2)

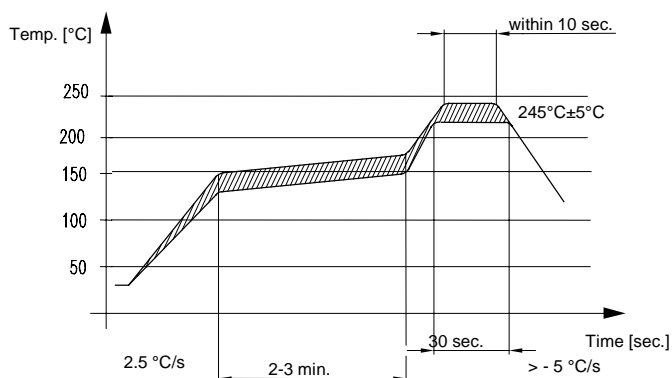
- Wettability to IEC 68-2-58: $\geq 75\%$ (after aging)

Soldering requirements

	Profile for eutectic SnPb solder paste	Profile for leadfree solder paste	
Soldering type	reflow	reflow	
Maximum soldering temperature (measuring point on top surface of the component)	235 (max. 2 sec.) 225 (max. 10 sec.)	260 (max. 2 sec.) 250 (max. 10 sec.)	°C °C

Recommended soldering conditions (infrared):


eutectic SnPb solder paste profile



leadfree solder paste profile

Delivery mode

- Blister tape acc. to IEC 286-3, PS, grey
- Pieces/tape: 4000

t.b.d.

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The information contained in this data sheet describes the type of component and shall not be considered as guaranteed characteristics. Purchase orders are subject to the General Conditions for the Supply of Products and Services of the Electrical and Electronics Industry recommended by the ZVEI (German Electrical and Electronic Manufacturers' Association), unless otherwise agreed.

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